Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole 1	Tolerance (+)	Hole Toler	ance (-)	Hole Length	Routed Path Length
	4	133.86mil (3.400mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn340						-	-
Ħ	12	11.81mil (0.300mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v60h30	Signal via 0.3 mm, 0.6mm					-	-
≎	25	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)						-	-
0	73	15.75mil (0.400mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	(Mixed)	(Mixed)					-	-
	114 Total														

Layer	Name	Material	Thickness	Constant	Gerber	Board Layer Stack			
Luyei		Widterial	HIICKIICSS	CONSTUNE		Bodid Edyer Stack			
	Top Overlay				GTO				
	Top Solder	SM-001	0.025mm	4	GTS				
	Top Surface Finish	PbSn	0.020mm						
1	Top Layer	CF-004	0.035mm		GTL				
	Dielectric 1	Core-043	1.499mm	4.3					
2	Bottom Layer	CF-004	0.035mm		GBL				
	Bottom Surface Finish	PbSn	0.020mm						
	Bottom Solder	SM-001	0.025mm	4	GBS				
	Bottom Overlay				GB0				

Total board thickness:

1.659mm

Client Name: Blues Wireless Project Name: Mobile Tracker Hat

File: Mobile Tracker Hat.PcbDoc

Rev: v6

### NOTES:

## UNLESS OTHERWISE SPECIFIED:

- 1. Board Dimension: 75.00 mm x 68.00 mm
- 2. Total Thickness: 1.6 mm +/- 10%
- 3. Board Material: FR-4, Tg130+
- 4. Copper Layers: 2, Weight: 1 oz
- 5. Soldermask Layers: Both, Color: Green (LPI preferred)
- 6. Legend Layers: Both, Color: White. (LPI preferred)
- 7. Finish: ENIG
- 8. Fabricate PCB According to IPC-6012 Class 2
- 9. 1.5 mm (0.06") maximum radius on any inside corner.

### SPECIAL REQUIREMENTS:

#### VENDOR NOTES:

- 10. Route board shape and any cut outs per Board Outline layer.
- 11. Place Manufacturer Mark and Date Code on bottom
- 12. Boards must pass visual inspection per IPC-A-600 Class 2

Engineering Contact: joseph@toybuilderlabs.com

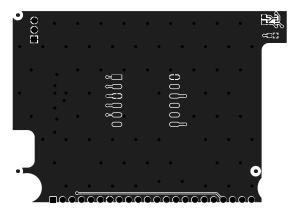


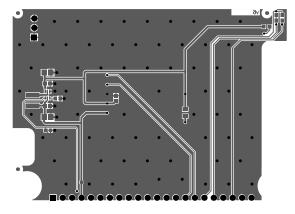
Blues Wireless Mobile Tracker Hat

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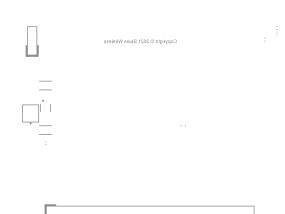


Blues Wireless Mobile Tracker Hat

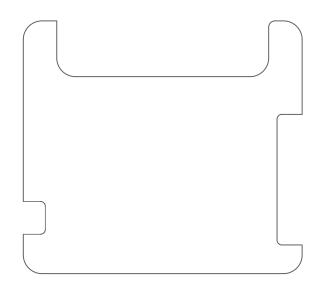




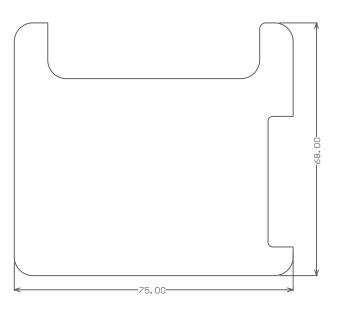












Layer	Name	Material	Thickness	Constant	Gerber	Board Layer Stack
	Top Overlay				GTO	
	Top Solder	SM-001	0.025mm	4	GTS	
	Top Surface Finish	PbSn	0.020mm			
1	Top Layer	CF-004	0.035mm		GTL	
	Dielectric 1	Core-043	1.499mm	4.3		
2	Bottom Layer	CF-004	0.035mm		GBL	
	Bottom Surface Finish	PbSn	0.020mm			
	Bottom Solder	SM-001	0.025mm	4	GBS	
	Bottom Overlay				GBO	

Total board thickness:

1.659mm

Client Name: Blues Wireless Project Name: Mobile Tracker Hat

File: Mobile Tracker Hat.PcbDoc

Rev: v6

## NOTES:

# UNLESS OTHERWISE SPECIFIED:

- 1. Board Dimension: 75.00 mm x 68.00 mm
- 2. Total Thickness: 1.6 mm +/- 10% 3. Board Material: FR-4, Tg130+

- S. Solder Maderal. 174-7, 1930
  Copper Layers: 2, Weight: 1 oz
  Soldermask Layers: Both, Color: Green (LPI preferred)
  Legend Layers: Both, Color: White. (LPI preferred)
- 7. Finish: ENIG
- 8. Fabricate PCB According to IPC-6012 Class 2 9. 1.5 mm (0.06") maximum radius on any inside corner.

## SPECIAL REQUIREMENTS:

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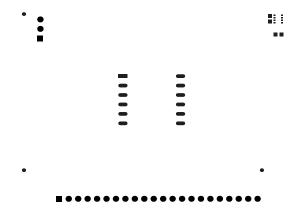
Engineering Contact: joseph@toybuilderlabs.com

'Fab Notes' 'Fab Notes'











	Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)	Hole Length	Routed Path Length
Γ		4	133.86mil (3.400mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn340				-	-
	Ħ	12	11.81mil (0.300mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v60h30	Signal via 0.3 mm, 0.6mm			-	i –
	\$	25	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)				-	i –
	0	73	15.75mil (0.400mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	(Mixed)	(Mixed)			-	_
Г		114 Total												

